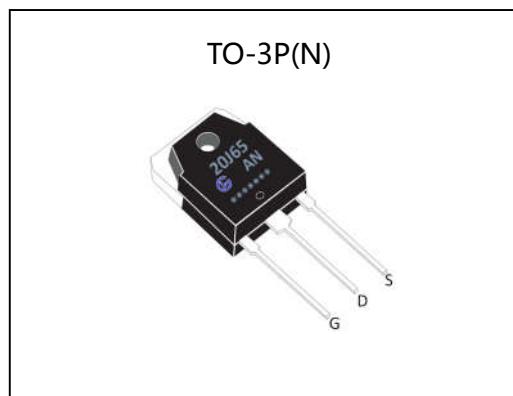


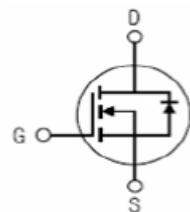
General Description:

GL20J65AN is the silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned Super-junction Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-3P(N), which accords with the RoHS standard.

V_{DSS}	650	V
I_D	20	A
$P_D(T_C=25^\circ C)$	166	W
$R_{DS(ON)}TYP$	0.14	Ω



Inner Equivalent Principium Chart



Features:

- Fast Switching
- Low Gate Charge and $R_{ds(on)}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply(UPS)
- Power Factor Correction(PFC)

Absolute (T_c= 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	650	V
I_D	Continuous Drain Current	20	A
I_{DM}^{a1}	Pulsed Drain Current	60	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}^{a2}	Single Pulse Avalanche Energy	532	mJ
P_D	Power Dissipation	166	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
T_L	MaximumTemperature for Soldering	300	°C

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JC}$	Junction-to-Case	0.75	°C/W
$R_{\theta JA}$	Junction-to-Ambient	55	°C/W



GL20J65AN

GL Silicon N-Channel Super-Junction Power MOSFET

Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	650	--	--	V
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=650\text{V}, V_{GS}=0\text{V}, T_a = 25^\circ\text{C}$	--	--	1.0	μA
		$V_{DS}=520\text{V}, V_{GS}=0\text{V}, T_a = 150^\circ\text{C}$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS} = +30\text{V}$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = -30\text{V}$	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}^{a3}$	Drain-to-Source On-Resistance	$V_{GS}=10\text{V}, I_D=10\text{A}$	--	0.14	0.16	Ω
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	--	3.0	V

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}^{a3}	Forward Transconductance	$V_{DS}=10\text{V}, I_D=20\text{A}$	--	18.8	--	S
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_D=25\text{V}$	--	1600	--	pF
C_{oss}	Output Capacitance	$f=1.0\text{MHz}$	--	14	--	
C_{rss}	Reverse Transfer Capacitance		--	225	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=350\text{V}, I_D=20\text{A}, V_{GS}=10\text{V} R_g=25\Omega$	--	48	--	ns
t_r	Rise Time		--	108	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	176	--	
t_f	Fall Time		--	50	--	
Q_g	Total Gate Charge	$I_D = 20\text{A}, V_{DD}=480\text{V}$	--	41	--	nC
Q_{gs}	Gate to Source Charge		--	8	--	
Q_{gd}	Gate to Drain ("Miller")Charge		--	15	--	



GL20J65AN

GL Silicon N-Channel Super-Junction Power MOSFET

Source-Drain Diode Characteristics

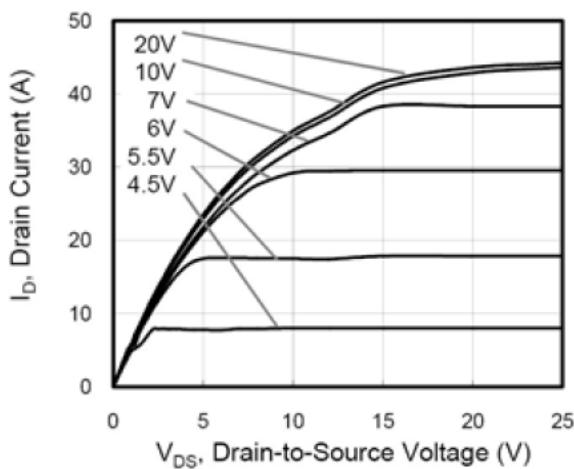
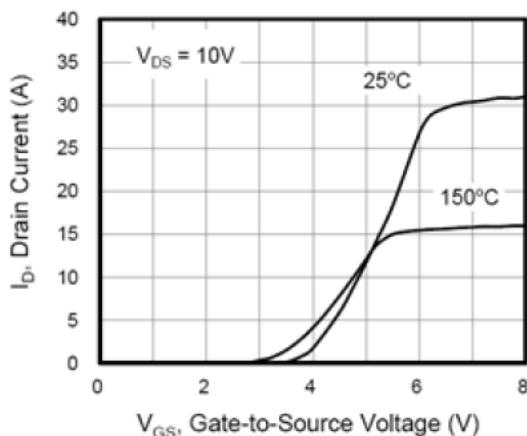
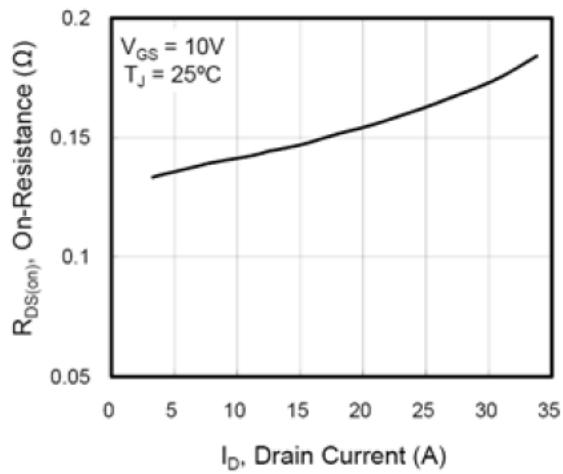
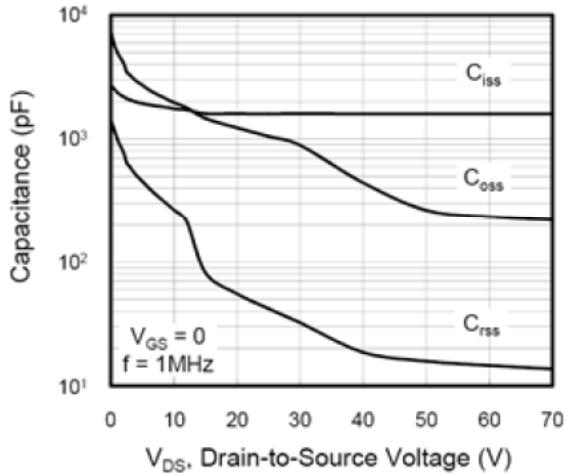
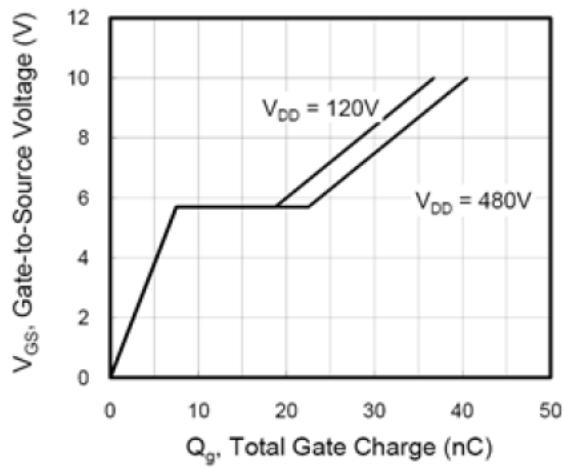
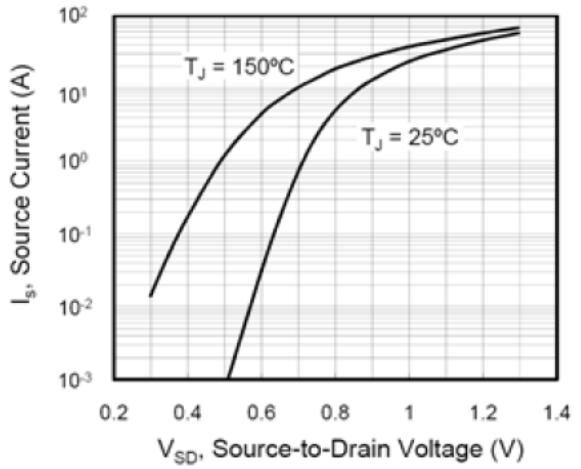
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	20	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	60	A
V _{SD}	Diode Forward Voltage	I _S =20A, V _{GS} =0V	--	--	1.5	V
t _{rr}	Reverse Recovery Time	I _S =20A, V _{GS} =0V	--	440	--	ns
Q _{rr}	Reverse Recovery Charge	I _S =I _F , d _i /d _t =100A/us	--	5.0	--	uC

Pulse width tp≤380μs, δ≤2%

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: I_{AS}=10A, V_{DD}=50V, R_G=25Ω, Starting T_J= 25°C

^{a3}: Pulse Test: Pulse width≤380us, Duty Cycle≤2%

Typical Characteristics
Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. On-Resistance vs. Drain Current

Figure 4. Capacitance

Figure 5. Gate Charge

Figure 6. Body Diode Forward Voltage


GL Silicon N-Channel Super-Junction Power MOSFET

Figure 7. On-Resistance vs.
Junction Temperature

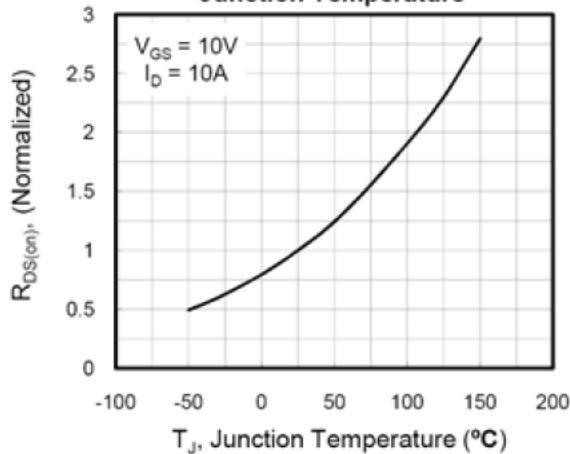


Figure 8. Threshold Voltage vs.
Junction Temperature

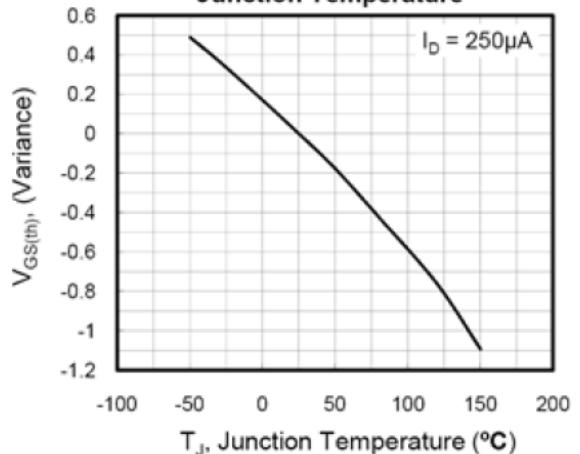


Figure 9. Transient Thermal Impedance
TO-3P

